

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

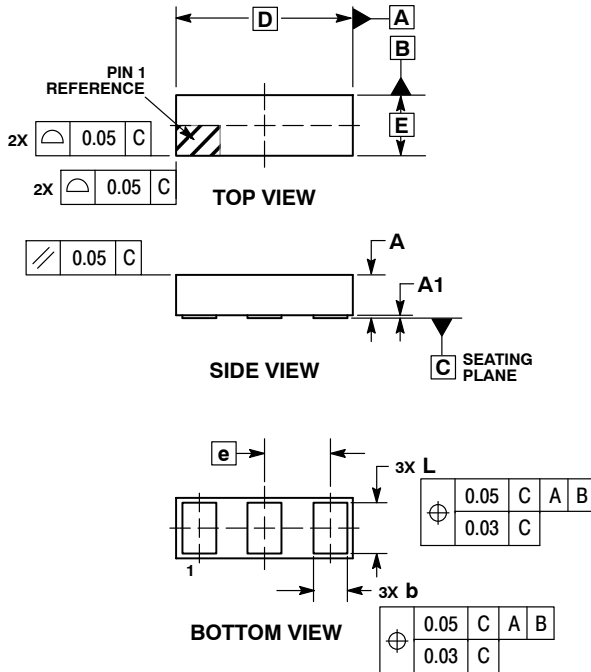
ON Semiconductor®



SCALE 16:1

DSN3, 0.73x0.25, 0.27P
CASE 152AW
ISSUE O

DATE 27 MAY 2015



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.

MILLIMETERS		
DIM	MIN	MAX
A	0.13	0.23
A1	---	0.03
b	0.11	0.17
D	0.73 BSC	
E	0.25 BSC	
e	0.27 BSC	
L	0.18	0.24

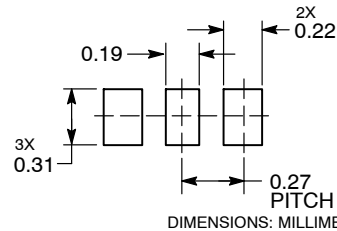
GENERIC MARKING DIAGRAM*



X = Specific Device Code
M = Month Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

RECOMMENDED SOLDER FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	DSN3, 0.73X0.25, 0.27P	PAGE 1 OF 1

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